- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

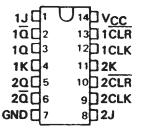
#### description

The '107 contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '107 is a positive pulse-triggered flip-flop. The J-K input data is loaded into the master while the clock is high and transferred to the slave and the outputs on the high-to-low clock transistion. For these devices the J and K inputs must be stable while the clock is high.

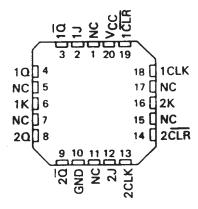
The 'LS107A contain two independent negative-edge-triggered flip-flops. The J and K inputs must be stable prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Q output low and the  $\overline{\mathbf{Q}}$  output high.

The SN54107 and the SN54LS107A are characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to 125 $\,^{\circ}\text{C}$ . The SN74107 and the SN74LS107A are characterized for operation from 0 $\,^{\circ}\text{C}$  to 70 $\,^{\circ}\text{C}$ .

SN54107, SN54LS107A . . . J PACKAGE SN74107 . . . N PACKAGE SN74LS107A . . . D OR N PACKAGE (TOP VIEW)



SN54LS107A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

'107
FUNCTION TABLE

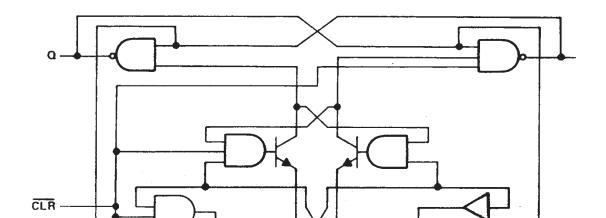
	INPU	TS		OUTF	UTS
CLR	CLK	J	Κ	Q	ā
L	×	Х	Х	L	Н
н	ır	L	L	₫0	$\bar{a}_0$
Н	T	н	L	н	L
н	. 1	L	н	L	Н
н	л	Н	н	TOG	GLE

'LS 107A FUNCTION TABLE

	INPU	TS		OUT	PUTS
CLR	CLK	J	κ	α	₫
L	×	Х	Х	L	H
н	1	L	L	$\sigma_0$	$\bar{a}_0$
н	4	Н	L	н	L
н	1	L	Н	L	н
н⊦	4	H.	Н	TOG	GLE
н	н	Х	×	△0	$\overline{a}_0$

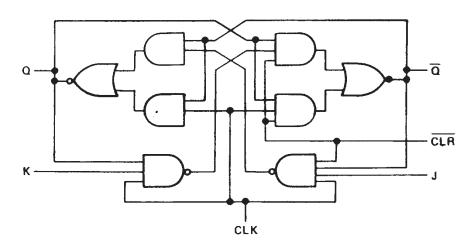


# logic diagrams (positive logic)



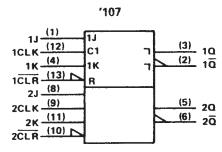
'LS107A

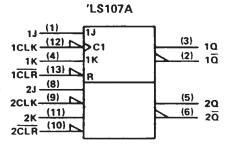
CLK



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#### logic symbols†



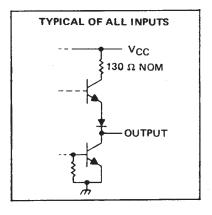


<sup>†</sup>These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, and N packages.

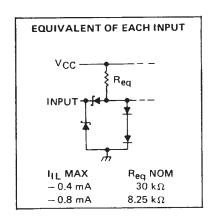
#### schematic of inputs and outputs

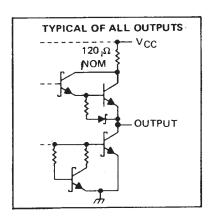
**EQUIVALENT OF EACH INPUT** V<sub>C</sub>C INPUT IIL MAX R<sub>eq</sub> NOM - 1.6 mA 4kΩ - 3.2 mA  $2 k\Omega$ 





'LS107A





# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: '107	5.5 V
Input voltage. 107	7 V
'LS107A	55°C 40 125°C
Operating free-air temperature range: SN54'	55 C to 125 C
SN74'	
Storage temperature range	$\dots = 65^{\circ}$ C to $150^{\circ}$ C

NOTE 1: Voltage values are with respect to network ground terminal.



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#### recommended operating conditions

			SN54107				SN7410	)7	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			8.0	٧
ЮН	High-level output current				- 0.4			- 0.4	mA
IOL	Low-level output current				16			16	mA
		CLK high	20			20			
tw	Pulse duration	CLK low	47			47			ns
		CLR low	25			25			
t <sub>su</sub>	Input setup time before CLK1		0			0			ns
th	Input hold time-data after CLK1		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA C	RAMETER		TEST CONDITI	ovet		SN5410	7		SN7410	7	
FAF	AMETER		TEST CONDITI	ONS.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
$v_{IK}$		V <sub>CC</sub> = MIN,	I <sub>1</sub> = - 12 mA				- 1.5			<b>– 1.5</b>	V
V <sub>OH</sub>		V <sub>CC</sub> = MIN, I <sub>OH</sub> = - 0.4 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V,	2.4	3.4		2.4	3.4		V
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 16 mA	V <sub>IH</sub> = 2 V,	V <sub>1L</sub> = 0.8 V,		0.2	0.4		0.2	0.4	٧
l <sub>l</sub>		V <sub>CC</sub> = MAX,	V <sub>1</sub> = 5.5 V				1			1	mA
1	J or K	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.4 V				40			40	
ΊΗ	All other	VCC = MAA,	V   = 2.4 V				80			80	μΑ
1	J or K	\/ MAY	V = 0.4 V				- 1.6			- 1.6	
ΙΙL	All other	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				- 3.2			- 3.2	mA
los §		V <sub>CC</sub> = MAX			- 20		- 57	- 18		- 57	mA
lcc1		V <sub>CC</sub> = MAX,	See Note 2			10	20		10	20	mA

<sup>&</sup>lt;sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open, I<sub>CC</sub> is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				15	20		MHz
<sup>†</sup> PLH	CLR	ā			16	25	ns
<sup>t</sup> PHL	CLA	Q	$R_{\perp} = 400 \Omega$ , $C_{\perp} = 15 pF$		25	40	ns
<sup>t</sup> PLH	CLK	Q or $\overline{\Omega}$			16	25	ns
<sup>t</sup> PHL	CLK	a or a			25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>^{\</sup>ddagger}$ All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25° C.

Not more than one output should be shorted at a time.

<sup>¶</sup>Average per flip-flop.

#### recommended operating conditions

			SN54LS107A			S	N74LS1	07A	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V <sub>C</sub> C	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			8.0	V
<sup>1</sup> ОН	High-level output current			-	- 0.4			- 0.4	mA
†OL	Low-level output current				4			8	mA
f <sub>clock</sub>	Clock frequency		0		30	0		30	MHz
	Dulan duranian	CLK high	20			20			
t <sub>w</sub>	Pulse duration	CLR low	25		;	25			ns
	0	data high or low	20			20			
<sup>t</sup> su	Setup time before CLK+	CLR inactive	25			25		-	ns
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			507 00MP17101	ust	SN	154LS10	7A	SN	174LS10	)7A	UNIT
PA	RAMETER	<b>!</b>	EST CONDITIO	45'	MIN	TYP ‡	MAX	MIN	TYP‡	MAX	UNII
VIK		V <sub>CC</sub> = MIN,					- 1.5			<b>– 1.5</b>	V
Vон		V <sub>CC</sub> = MIN, I <sub>OH</sub> = 0.4 mA	V <sub>IH</sub> = 2 V,	VIL = MAX,	2.5	3.4		2.7	3.4		٧
.,		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 4 mA	VIL = MAX,	V <sub>IH</sub> = 2 V,		0.25	0.4		0.25	0.4	<b>&gt;</b>
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 8 mA	VIL = MAX,	V <sub>IH</sub> = 2 V,					0.35	0.5	
	J or K						0.1			0.1	
1	CLR	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.3			0.3	mA
	CLK						0.4			0.4	
• • • •	J or K						20			20	
ЧН	CLR	V <sub>CC</sub> = MAX,	V1 = 2.7 V				60			60	μΑ
	CLK	]					80			80	
	J or K		V = 0.4.V				- 0.4			- 0.4	mA
HL	CLR or CLK	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				- 0.8			- 0.8	100
los§		V <sub>CC</sub> = MAX,	See Note 4		- 20		- 100	- 20		- 100	mA
Icc (	Total)	V <sub>CC</sub> = MAX,	See Note 2			4	6		4	6	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COM	TEST CONDITIONS				UNIT
fmax					30	45		MHz
tPLH	<del></del>		$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 15 pF		15	20	ns
tPHL	CLR or CLK	Q or Q				15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>\</sup>ddagger$  All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open,  $I_{CC}$  is measured with the Q and  $\overline{Q}$ , outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V<sub>O</sub> = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

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5-Jun-2023

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00203BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	Samples
M38510/00203BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	Samples
M38510/00203BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	Samples
SN54107J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54107J	Samples
SN54107J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54107J	Samples
SN74LS107AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS107A	Samples
SN74LS107AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS107A	Samples
SN74LS107AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS107AN	Samples
SN74LS107AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS107AN	Samples
SN74LS107ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS107A	Samples
SN74LS107ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS107A	Samples
SNJ54107J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54107J	Samples
SNJ54107J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54107J	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".



## **PACKAGE OPTION ADDENDUM**

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RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

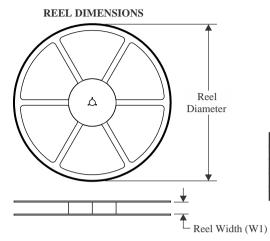
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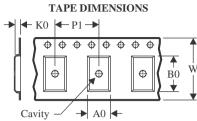
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# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

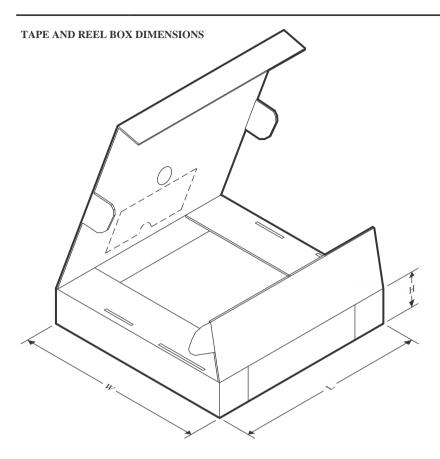


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS107ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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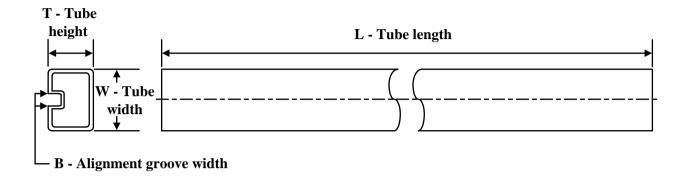
#### \*All dimensions are nominal

Device		Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS107ANS	R	SO	NS	14	2000	356.0	356.0	35.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LS107AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS107AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS107AN	N	PDIP	14	25	506	13.97	11230	4.32

# N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

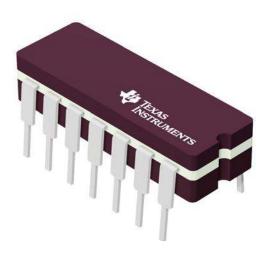
### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



CERAMIC DUAL IN LINE PACKAGE



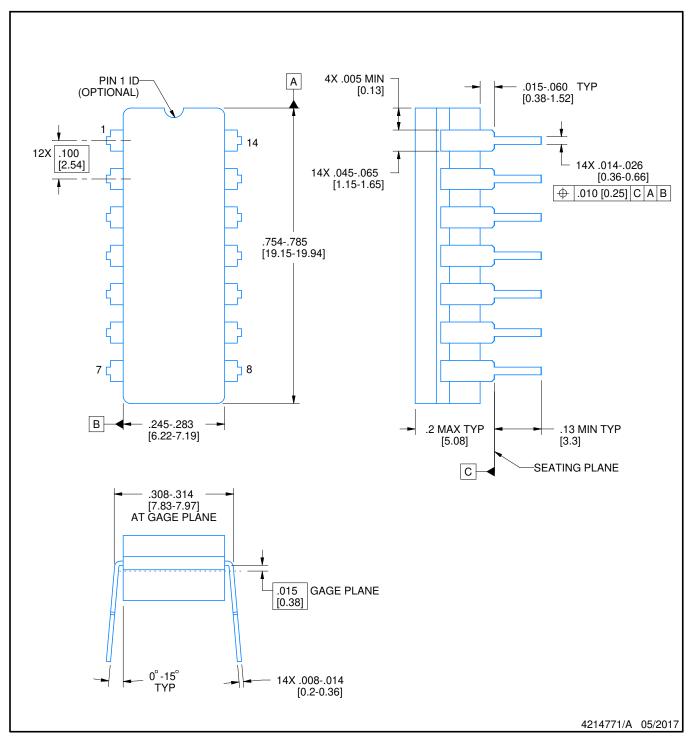
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





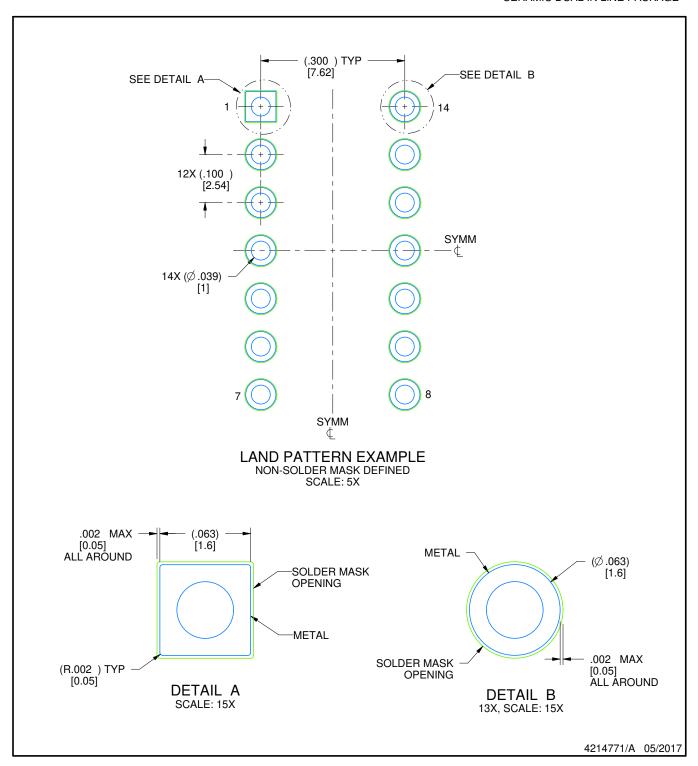
CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a certain is using glass int.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# D (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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